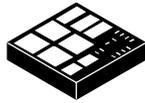


MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

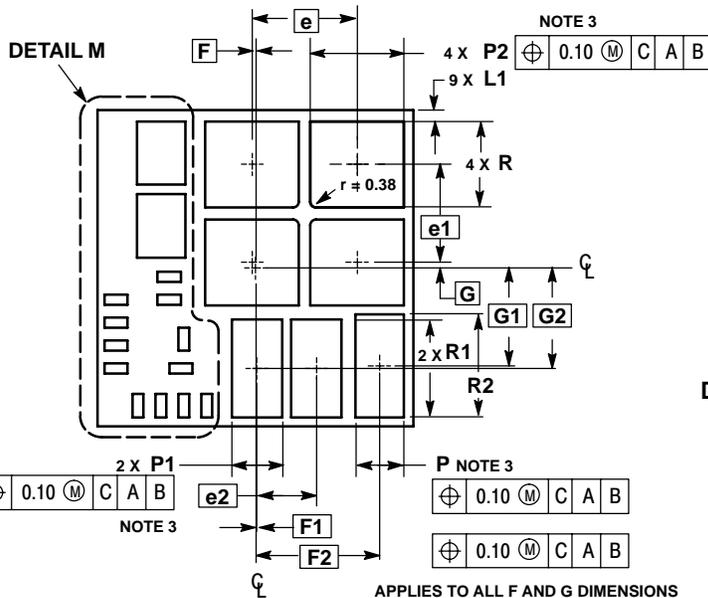
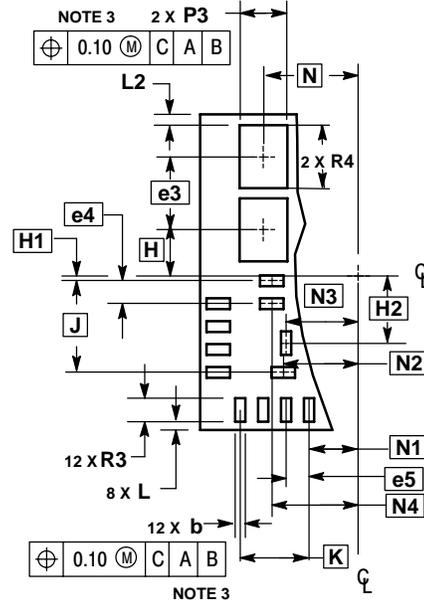
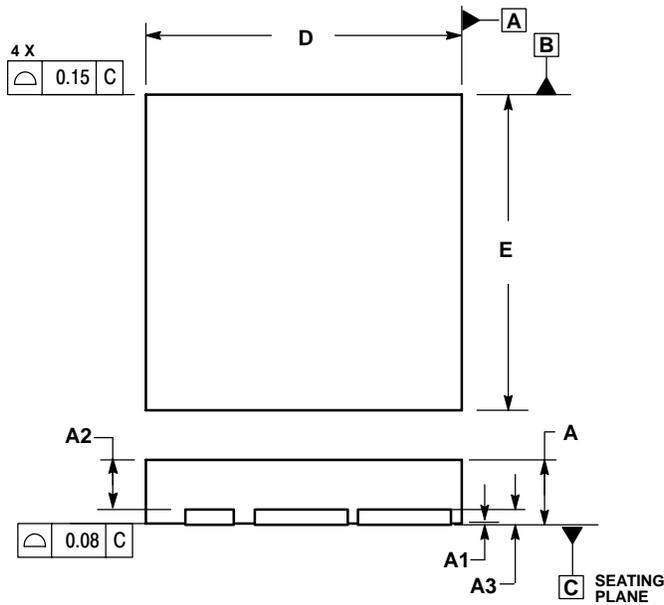
ON Semiconductor®



SCALE 1:1

JUPITER - PInPAK™
10.5x10.5 PLLP
CASE 500-02
ISSUE B

DATE 31 MAR 2003



NOTE 3
 $\oplus 0.10 \text{ M } \text{C A B}$
 APPLIES TO ALL H AND N DIMENSIONS
 DETAIL M

DIMENSION TABLE AND MARKING DIAGRAM
ON FOLLOWING PAGE

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DESCRIPTION:	10.5 X 10.5 PLLP, PInPAK	PAGE 1 OF 3

**JUPITER – PInPAK
10.5x10.5 PLLP
CASE 500–02
ISSUE B**

DATE 07 MAR 2003

**GENERIC MARKING
DIAGRAM**



xx = Specific Device Code
 YY = Year
 WW = Work Week

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION APPLIES TO PLATED TERMINAL IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL EDGE.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	2.000	2.200
A1	0.000	0.050
A2	1.500	1.700
A3	0.508 REF	
D	10.500 BSC	
E	10.500 BSC	
b	0.306	0.406
e	3.496 BSC	
e1	3.261 BSC	
e2	1.969 BSC	
e3	2.424 BSC	
e4	0.762 BSC	
e5	0.762 BSC	
F	0.124 BSC	
F1	0.037 BSC	
F2	4.114 BSC	
G	0.229 BSC	
G1	3.200 BSC	
G2	3.289 BSC	
H	1.424 BSC	
H1	0.283 BSC	
H2	2.188 BSC	
J	3.048 BSC	
K	2.286 BSC	
L	0.154	0.354
L1	0.230	0.430
L2	0.230	0.430
N	2.936 BSC	
N1	1.495 BSC	
N2	2.197 BSC	
N3	2.361 BSC	
N4	2.663 BSC	
P	1.512	1.712
P1	1.589	1.789
P2	2.996	3.196
P3	1.512	1.712
R	2.761	2.961
R1	3.161	3.361
R2	3.339	3.539
R3	0.689	0.889
R4	2.094	2.244

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